



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| L | 4.5mm +/-0.3mm |
| W | 3.2mm +/-0.3mm |
| T | 3.3mm +/-0.4mm |
| B | 0.6mm +/-0.35mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 500 |

| General Information | |
|---------------------|---|
| Series | KONNEKT Comm COG |
| Style | KONNEKT |
| Description | SMD, MLCC, KONNEKT, Ultra-Stable, Class I |
| Features | High Density Packaging |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Component Weight | 190 mg |
| Chip Size | 1812-2 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------|
| Capacitance | 0.44 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C |
| Dissipation Factor | 0.1% 1kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 1.136 GOhms |